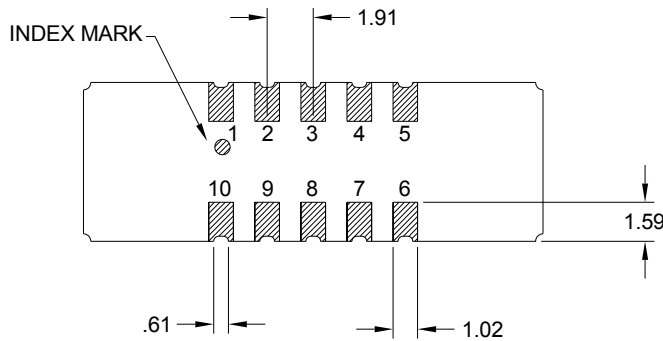
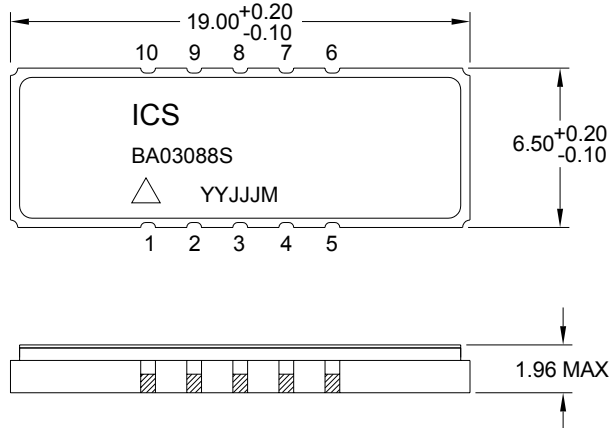


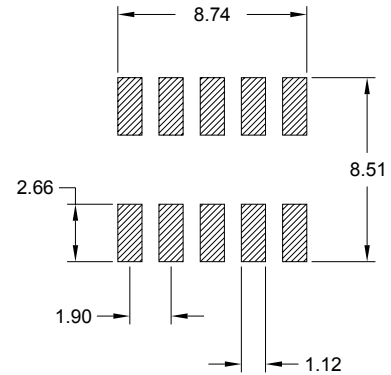


PACKAGE AND SUGGESTED PCB FOOTPRINT

PACKAGE INFORMATION



SUGGESTED PCB FOOTPRINT

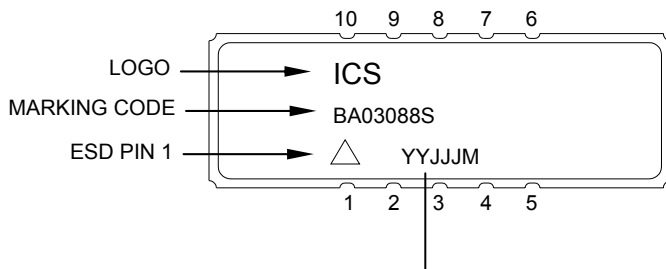


PIN NO.	DESCRIPTION
10	INPUT
5	OUTPUT
1,2,3,4,6,7,8,9	GROUND

NOTES:
DIMENSIONS SHOWN ARE NOMINAL IN MILLIMETERS. ALL TOLERANCES ARE ± 0.15 MM EXCEPT OVERALL LENGTH AND WIDTH

Package Material:
Body: Al_2O_3 ceramic
Lid: Kovar, Ni plated
Terminations: Au plating 0.5-1.0 μ m, over a 2-6 μ m Ni plating

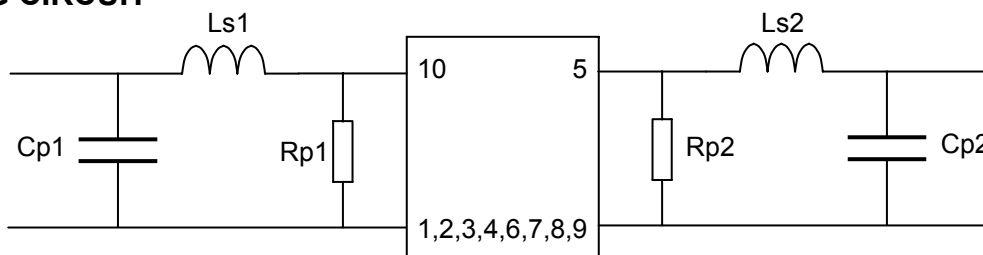
MARKING



The date code consists of:
YY = last two digits of year; JJJ = Julian day;
M = manufacturing site code



MATCHING CIRCUIT



Component values in 50Ω: Rp1 = 430 Ω Ls1 = 68 nH Cp1 = 56 pF
(Minimum inductor Q = 45) Rp2 = 300 Ω Ls2 = 68 nH Cp2 = 56 pF

Notes:

1. Optimum values may differ from these when using a different fixture or board layout. The values shown here are intended as a guide only.
2. Required component tolerances – resistors ±5%, inductors ±2%, capacitors ±5%.

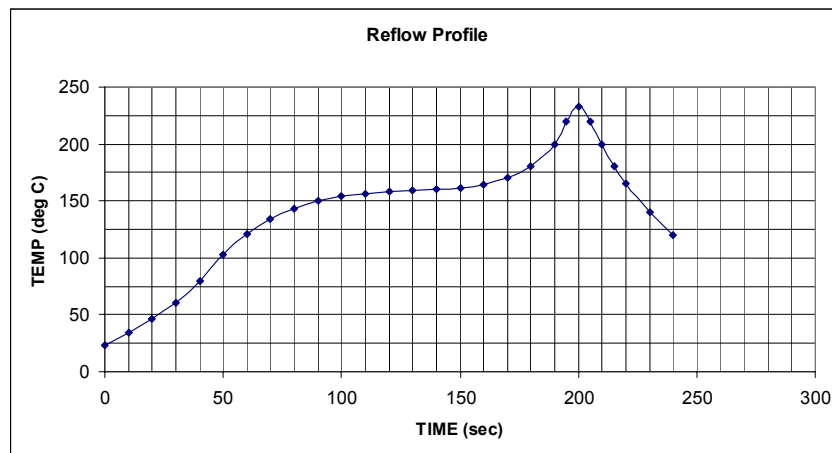
MAXIMUM RATINGS

Parameter	Min	Max	Units
Operating Temperature Range	-10	+50	°C
Storage Temperature Range	-45	+85	°C
Input Power Level		20	dBm
D. C. Voltage between Each Terminal		15	V



PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

Parameter	Qualification Conditions
Life Testing	High temperature bake at +85 °C for 168 hours.
Temperature Cycling	MIL-STD 883, Method 1010: -40 °C to +85 °C, 10 cycles, 10 minutes dwell at temperature extremes
Vibration	MIL-STD-202, Method 201A: 10 to 55 Hz, double amplitude of 0.06" for 2 hours in each axis.
Mechanical Shock	MIL-STD-883, Method 2002, Test Condition B: 1500 g, 3 impacts each axis
Solder Heat Resistance and Reflow Condition	Peak temperature 240+/-5 °C for 10 seconds. Pre-heat: 150-170 °C for 60 to 90 seconds. Peak dwell: over 200 °C for 23 to 26 seconds. Handling: Class 1 per MIL-STD-1686 Reflow Profile is shown at the bottom of this table.
Lead Integrity	MIL-STD 883 Method 2004, Condition D 8 oz for 30 seconds.
Solderability	MIL-STD-883 Method 2003: 245 °C +/-5 °C; 95% coverage; no steam aging
Hermeticity	MIL-STD 883 Method 1014: Condition A2 and Condition C (no bomb)
ESD Classification	Class I per MIL-STD-883 Method 3015
Precautions	Do not subject devices to ultrasonic cleaning, which may cause deterioration and destruction of the device.



ISO 9001
Registered